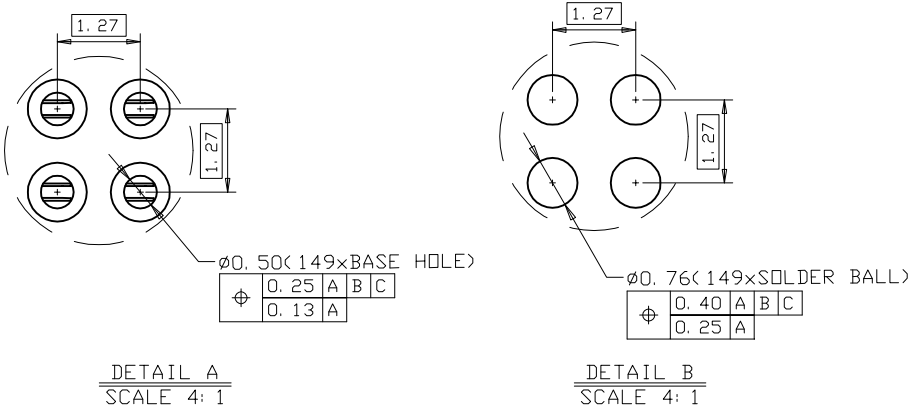


REV.	ECN. NO.	APPD.
A	BC-18-0034109	Nick Lin

- NOTES:
1. MATERIAL:
BASE: THERMOPLASTIC, UL94V-0
CONTACT: COPPER ALLOY
PLATING 150" MIN Au PLATING ON CONTACT AREA
500" MIN Ni PLATING OVER WHOLE CONTACT
 2. DIMENSIONS SHALL BE INTERPRETED PER ASME Y14.5-2009.
 3. LOT IDENTIFICATION CODE IS LOCATED AS SHOWN
 4. THICKNESS OF SOCKET (FROM PACKAGE'S SEATING PLANE TO BOTTOM OF SOLDER BALL) :
2.70±0.20 mm AFTER SOLDERING PROCESS.
 5. HARMFUL MATERIAL CONTROL PLEASE FOLLOW DOC.: "SG-2B0-030".
 6. PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY.
 7. THE CONCENTRATIONS OF BR & CL CAN SATISFY THE REQUIREMENTS OF HALOGEN-FREE IN DOCUMENT SG-2B0-030.



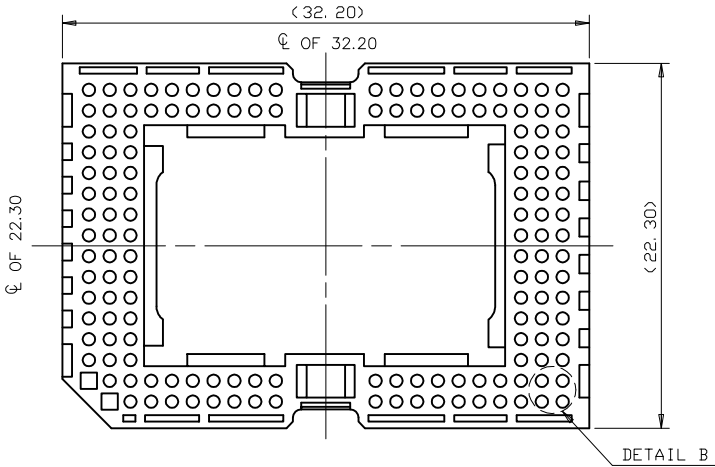
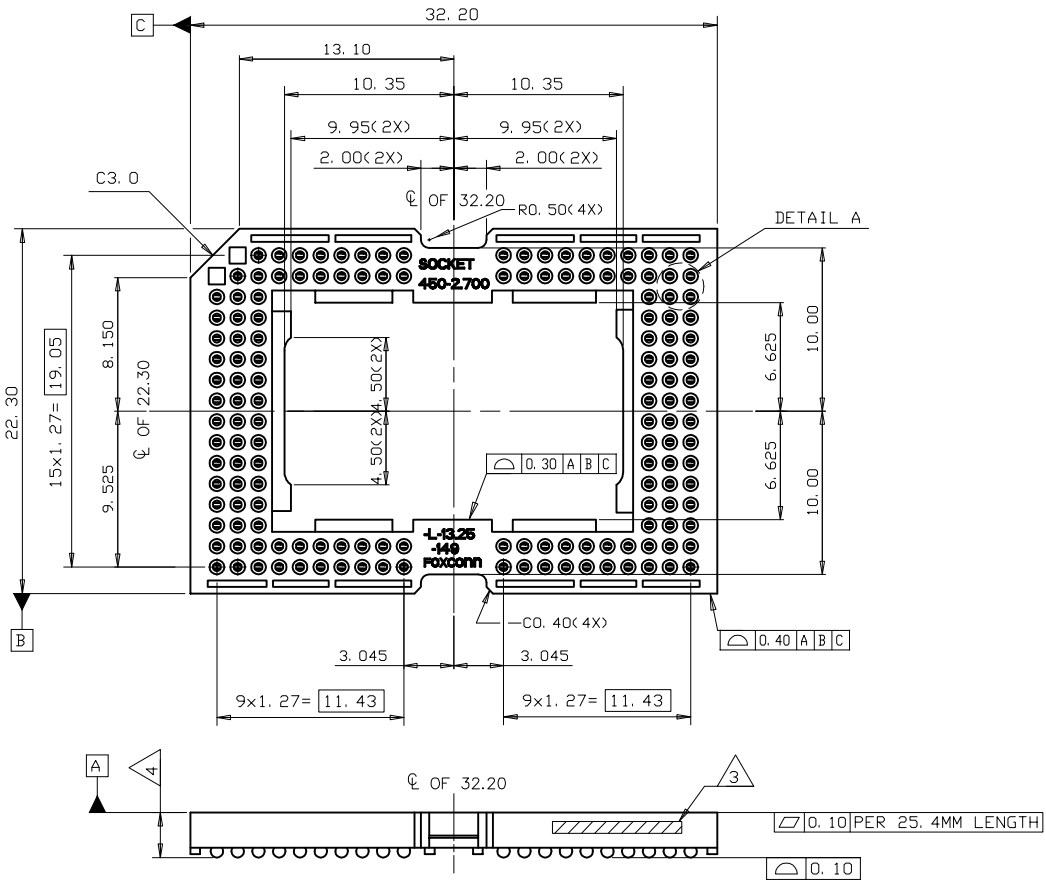
PRODUCT NO.	COMPONENT NAME	MATERIAL	Q' TY	NOTE
PL01497-11ZZ1-4H	BASE	THERMOPLASTIC	1	BLACK
	CONTACT	COPPER ALLOY	149	Ni, Au
	SOLDER BALL	Sn	149	NATURAL
	PLASTIC CAP	THERMOPLASTIC	1	BLACK

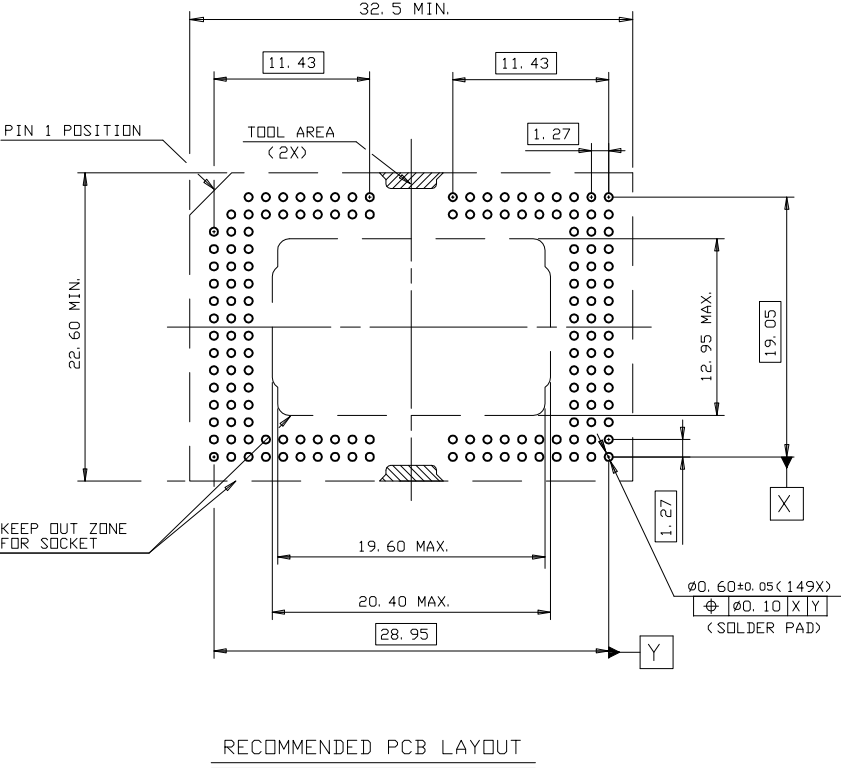
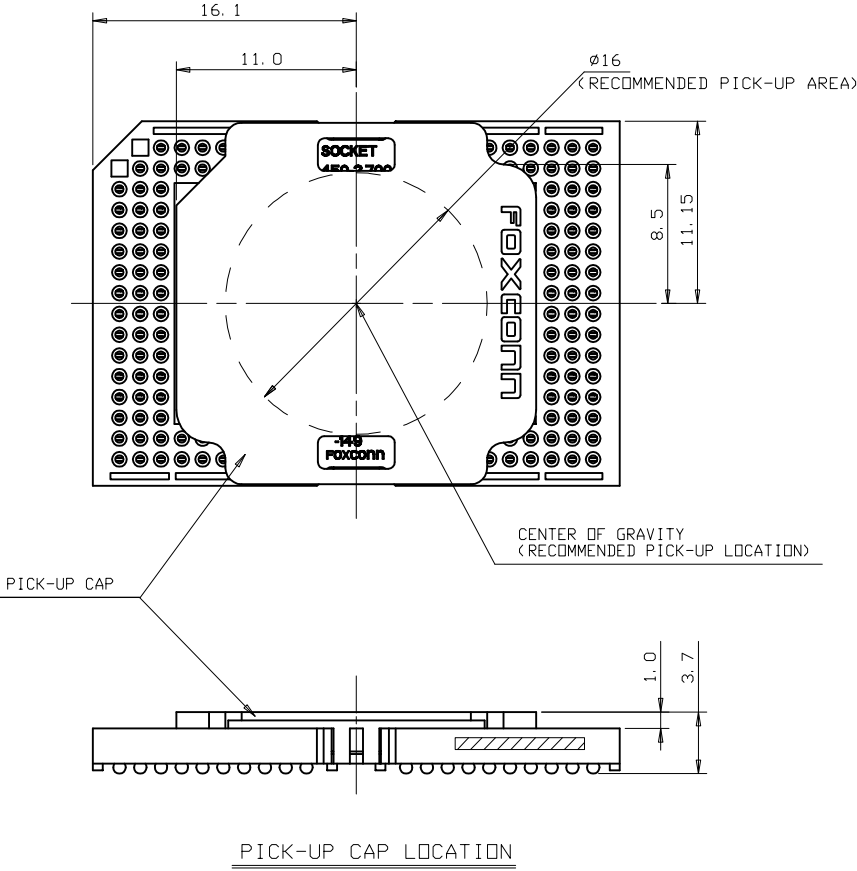
X. ±	X. ° ± 1 °	UNITS	NAME (INTENDED USE)	
.X ± 0.20	.X ° ±	MAT'L	TI SERIES 450	
.XX ± 0.10	.XX ° ±	FINISH	PART NO. (INTENDED USE) PL01497-11ZZ1-4H	
.XXX ± 0.10	.XXX ° ±	Q' TY	APPD: Nick Lin CHKD: Yusan Hsiao DRAW: Bryant Liu 08/18'18	
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P/N	DESCRIPTION
PL01497-11ZZ1-4H	LF SN-AG-CU TYPE

A
B
C
D
E

A
B
C
D
E





X. ±	X. ° ± 1 °	UNITS mm	NAME (INTENDED USE)	 FOXCONN INTERCONNECT TECHNOLOGY LIMITED. CLASS: ☐CONFIDENTIAL ☐SECRET ☒GENERAL TITLE: CUSTOMER DRAWING FOR AUTOMOTIVE DMD149 LIF SOCKET DWG NO.: 309-0000-1424 SCALE SHEET REV. 1:1 2/2 A
.X ± 0.20	.X ° ±	MAT'L 	PART NO. (INTENDED USE)	
.XX ± 0.10	.XX ° ±		PL01497-11ZZ1-4H	
.XXX ± 0.10	.XXX ° ±	FINISH	APPD: Nick Lin	
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			DRAW: Bryant Liu 08/18'18	

P/N	DESCRIPTION
PL01497-11ZZ1-4H	LF SN-AG-CU TYPE